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FEB 24 2006

MEG 01-015

AMENDMENTS

IN THE CLAIMS

1-241. (canceled)

242. (currently amended) A chip packaging method comprising:  
joining a die and a substrate;  
after said joining said die and said substrate, depositing a passive device over said  
substrate, wherein said passive device has a portion not over said die; and  
separating said substrate.

243. (currently amended) A chip packaging method comprising:  
joining a die and a substrate, ~~said die having a top surface at a horizontal level;~~  
after said joining said die and said substrate, depositing a passive device over said  
~~substrate horizontal level,~~ wherein said passive device has a first end connected down to said die  
and a second end connected to a topmost pad of said chip package; and  
separating said substrate.

244. (currently amended) A chip packaging method comprising:  
providing a die having a top surface at a horizontal level;  
depositing a passive device over said horizontal level, wherein said passive device has a  
portion not over said die; and

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depositing a trace over said horizontal level, wherein said trace has a portion not over said  
die, and extends to a place under which said die does not exist.